

ENGINEERING PRACTICES STUDY

PROJECT NUMBER: 5998-2009-011

TITLE:

Engineering Practices Study to Review IPC-2226 "Sectional Design Standard for High Density Interconnect (HDI) Printed Boards" for DoD Adoption

3 February 2009

FINAL REPORT

Prepared by:

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ATTCH 1

I. OBJECTIVES: The objective of this study was to obtain from the military users either comments or concurrence regarding the proposed adoption of IPC-2226, a non-Government standard (NGS). The subject NGS is published by the IPC – Association Connecting Electronics Industries (IPC).

II. BACKGROUND: The subject NGS is planned to be referenced by several specification sheets within MIL-PRF-31032 for the baseline design requirements for PB's containing High Density interconnects structures.

III. RESULTS: The subject NGS was distributed by electronic mail message to 20 Department of Defense and Government activities requesting their input (comments or concurrence) regarding the contents of subject NGS document. The review cycle was 45 days. All responses were in concurrence with the adoption of the subject NGS document. There were no negative or valid essential comments submitted.

IV. CONCLUSIONS: Based upon the fact that there were not any negative comments with the adoption, a DoD notice of adoption for the subject NGS document should be issued.

V. RECOMMENDATIONS: After this final report is coordinated with the Department of Defense and Government activities that responded, DSCC will initiate a standardization project to prepare a notice of adoption for the subject NGS document without additional coordination. Attached is a proposed DoD notice of adoption for IPC-2226.

DRAFT DATED 2 February 2009

IPC-2226

ADOPTION NOTICE

IPC-2226 "Sectional Design Standard for High Density Interconnect (HDI) Printed Boards", was adopted on **DAY MONTH YEAR** for use by the Department of Defense (DoD). Proposed changes by DoD activities must be submitted to the DoD Adopting Activity: Defense Logistics Agency, Defense Supply Center, Columbus, ATTN: DSCC-VAC, P.O. Box 3990, Columbus OH 43218-3990. Copies of this standard may be purchased or downloaded from the IPC – Association Connecting Electronics Industry (IPC), 3000 Lakeside Drive, Suite 309 S, Bannockburn, IL 60015–1249 or at URL: <http://www.ipc.org>.

Custodians:
Army - CR
Navy - EC
Air Force - 85

Preparing activity:
DLA - CC

Project: 5998-Year-NUM

NOTE: The activities listed above were interested in this document as of the date of this document. Since organizations and responsibilities can change, you should verify the currency of the information above using the ASSIST Online database at <http://assist.daps.dla.mil/>.

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